



# 6th International Summit for Packaging Industry 5<sup>TH</sup> RESEARCH CONCLAVE ON PACKAGING 5S-AI 14<sup>th</sup> March, 2026 Eros Hotel, Nehru Place, New Delhi

## About the International Summit for the Packaging Industry

The 6th International Summit for the Packaging Industry is a prestigious gathering of industry leaders, innovators, researchers, and policymakers. This annual event provides a platform to discuss and explore emerging trends, advancements, and challenges in the global packaging industry.

### Key Highlights of the Summit:

- Expert keynote sessions from global leaders in packaging.
- Panel discussions on sustainability, innovation, and technology.
- Networking opportunities with industry pioneers and researchers.

As a concurrent event to the International Summit for the Packaging Industry, the Research Conclave is a dynamic platform designed to spotlight groundbreaking research and innovation in packaging.

The conclave is dedicated to fostering collaboration between academia and industry, offering students, scholars, and professionals the opportunity to present their research through Oral and Poster Presentations.

### Why Participate in the Research Conclave?

- Showcase your research to an audience of industry leaders and innovators.
- Gain recognition through awards and potential publication in the Springer - Journal of Packaging Technology & Research (JPTR).
- Connect with peers and professionals to exchange ideas and insights.

## 5<sup>TH</sup> RESEARCH CONCLAVE

### ABSTRACT SUBMISSION GUIDELINES

To participate in the Research Conclave, submit on following guidelines:

#### For Oral Presentations :

- Length: Abstracts must not exceed 250 words.
- Format: Submit in MS Word, using Times New Roman, font size 12, and double spacing.
- Content: Include the title, presenter's name, affiliation, keywords, and contact details.

#### For Poster Presentations :

- Length : Abstracts must not exceed 250 words.
- Poster size: 42" x 55".
- Posters should include the title, presenter's name, affiliation, keywords, mailing address, and a summary of key findings.

## PACKAGING 5S-AI

SAFE

SECURE

SMART

STANDARDIZED

SUSTAINABLE

ARTIFICIAL INTELLIGENCE

Last Date of  
Abstract Submission  
15th February, 2026

Send your abstracts to :

<https://iip-ispi.com/register/registration.php>  
rcispi2026@gmail.com, iipdelhi@iip-in.com

- The 10 best abstracts will be selected for oral presentations.
- Both oral and poster presentations will be judged for awards.

### Delegate Fee

Categories	Early Bird (till 5th Feb. - 2026)	Registration Fee (6th Feb. - 6th Mar. - 2026)	On Spot	OVERSEAS (\$) (Inclusive of all Taxes)
Academic and R&D Institution	₹7,000	₹8,000	₹9,000	\$ 200
Student & Research Scholars	₹2,500 (for one day only)	₹6,000	₹7,000	\$ 200

Early bird discount is only for Research Conclave & above rates are exclusive of 18% GST

## AWARDS AND RECOGNITION

Participants stand a chance to win exciting prizes for their outstanding work:

1st Prize: E-Book Coupon worth €250

2nd Prize: E-Book Coupon worth €200

3rd Prize: E-Book Coupon worth €150

Also



BEST RESEARCH PAPER WILL BE PUBLISHED IN SPRINGER - JOURNAL OF PACKAGING TECHNOLOGY & RESEARCH (JPTR)



### Why You Should Join

- ✓ Be part of a premier event that blends academia and industry.
- ✓ Showcase your research and innovation to global leaders.
- ✓ Access invaluable networking opportunities with professionals and peers.
- ✓ Gain visibility and recognition for your work in packaging technology.

NAAS rating: 4.92

Register  
NOW  
for  
participation

Join Us to Redefine Packaging for a Sustainable Future!

The Indian Institute of Packaging invites you to a platform where innovation, collaboration, and recognition converge. Don't miss this opportunity to contribute, connect, and lead the change in packaging technology.

For more information please visit  
[www.iip-ispi.com](http://www.iip-ispi.com)